

## Fast Switching Emitter Controlled Diode

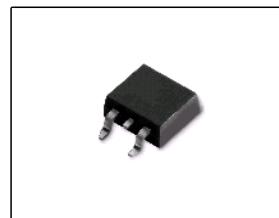


### Feature

- 600V Emitter Controlled technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- 175°C operating temperature
- Easy paralleling
- Qualified according to JEDEC<sup>0)</sup> for target applications

### Product Summary

|            |     |    |
|------------|-----|----|
| $V_{RRM}$  | 600 | V  |
| $I_F$      | 15  | A  |
| $V_F$      | 1.5 | V  |
| $T_{jmax}$ | 175 | °C |



PG-T0263-3

| Type     | Package    | Ordering Code | Marking | Pin 1 | PIN 2 | PIN 3 |
|----------|------------|---------------|---------|-------|-------|-------|
| IDB15E60 | PG-T0263-3 | -             | D15E60  | NC    | C     | A     |

**Maximum Ratings**, at  $T_j = 25$  °C, unless otherwise specified

| Parameter   | Symbol    | Value      | Unit |
|---|-----------|------------|------|
| Repetitive peak reverse voltage   | $V_{RRM}$ | 600        | V    |
| Continuous forward current<br>$T_C = 25$ °C   | $I_F$     | 29.2       | A    |
| $T_C = 90$ °C   |           | 19.6       |      |
| Surge non repetitive forward current<br>$T_C = 25$ °C, $t_p = 10$ ms, sine halfwave           | $I_{FSM}$ | 60         | A    |
| Maximum repetitive forward current<br>$T_C = 25$ °C, $t_p$ limited by $t_{j,max}$ , $D = 0.5$ | $I_{FRM}$ | 45         | A    |
| Power dissipation<br>$T_C = 25$ °C  | $P_{tot}$ | 83.3       | W    |
| $T_C = 90$ °C   |           | 47.2       |      |
| Operating junction temperature  | $T_j$     | -40...+175 |      |
| Storage temperature   | $T_{stg}$ | -55...+150 | °C   |
| Soldering temperature<br>1.6mm (0.063 in.) from case for 10 s                                 | $T_s$     | 260        |      |

**Thermal Characteristics**

| Parameter                                       | Symbol     | Values |      |      | Unit |
|---|------------|--------|------|------|------|
|   |            | min.   | typ. | max. |      |
| <b>Characteristics</b>                          |            |        |      |      |      |
| Thermal resistance, junction - case             | $R_{thJC}$ | -      | -    | 1.8  | K/W  |
| Thermal resistance, junction - ambient, leaded  | $R_{thJA}$ | -      | -    | 62   |      |
| SMD version, device on PCB:<br>@ min. footprint | $R_{thJA}$ | -      | -    | 62   |      |
| @ 6 cm <sup>2</sup> cooling area <sup>1)</sup>  |            | -      | 35   | -    |      |

**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

| Parameter  | Symbol | Values |      |      | Unit          |
|--|--------|--------|------|------|---------------|
|  |        | min.   | typ. | max. |               |
| <b>Static Characteristics</b>                                      |        |        |      |      |               |
| Reverse leakage current<br>$V_R=600\text{V}, T_j=25^\circ\text{C}$ | $I_R$  | -      | -    | 50   | $\mu\text{A}$ |
| $V_R=600\text{V}, T_j=150^\circ\text{C}$                           |        | -      | -    | 1250 |               |
| Forward voltage drop<br>$I_F=15\text{A}, T_j=25^\circ\text{C}$     | $V_F$  | -      | 1.5  | 2    | V             |
| $I_F=15\text{A}, T_j=150^\circ\text{C}$                            |        | -      | 1.5  | -    |               |

<sup>0</sup>J-STD20 and JESD22

<sup>1</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air.

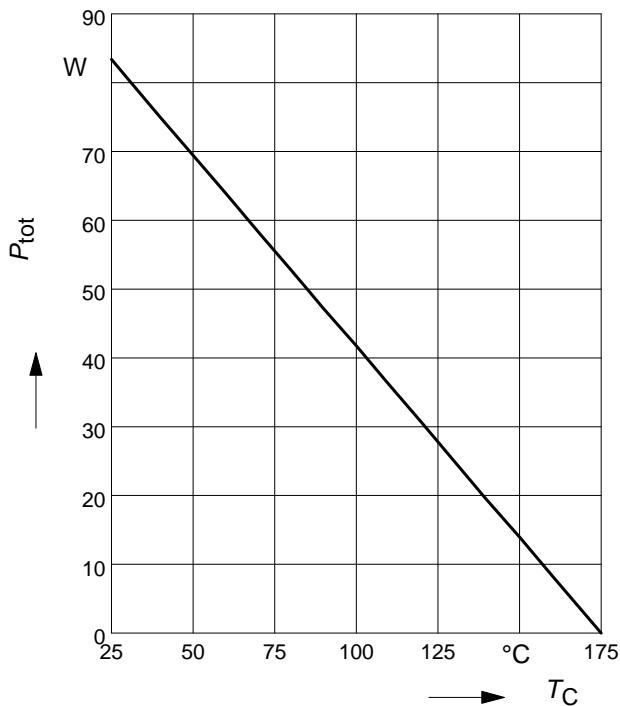
**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

| <b>Parameter</b>  | <b>Symbol</b> | <b>Values</b> |             |             | <b>Unit</b> |
|---|---------------|---------------|-------------|-------------|-------------|
|   |               | <b>min.</b>   | <b>typ.</b> | <b>max.</b> |             |
| <b>Dynamic Characteristics</b>  |               |               |             |             |             |
| Reverse recovery time<br>$V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=25^\circ\text{C}$            | $t_{rr}$      | -             | 87          | -           | ns          |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=125^\circ\text{C}$                                    |               | -             | 124         | -           |             |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=150^\circ\text{C}$                                    |               | -             | 131         | -           |             |
| Peak reverse current<br>$V_R=400\text{V}, I_F = 15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=25^\circ\text{C}$           | $I_{rrm}$     | -             | 13.7        | -           | A           |
| $V_R=400\text{V}, I_F = 15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=125^\circ\text{C}$                                  |               | -             | 16.4        | -           |             |
| $V_R=400\text{V}, I_F = 15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=150^\circ\text{C}$                                  |               | -             | 19.3        | -           |             |
| Reverse recovery charge<br>$V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=25^\circ\text{C}$          | $Q_{rr}$      | -             | 595         | -           | nC          |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=125^\circ\text{C}$                                    |               | -             | 995         | -           |             |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=150^\circ\text{C}$                                    |               | -             | 1104        | -           |             |
| Reverse recovery softness factor<br>$V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=25^\circ\text{C}$ | $S$           | -             | 3.6         | -           |             |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=125^\circ\text{C}$                                    |               | -             | 4.3         | -           |             |
| $V_R=400\text{V}, I_F=15\text{A}, di_F/dt=1000\text{A}/\mu\text{s}, T_j=150^\circ\text{C}$                                    |               | -             | 4.5         | -           |             |

**1 Power dissipation**

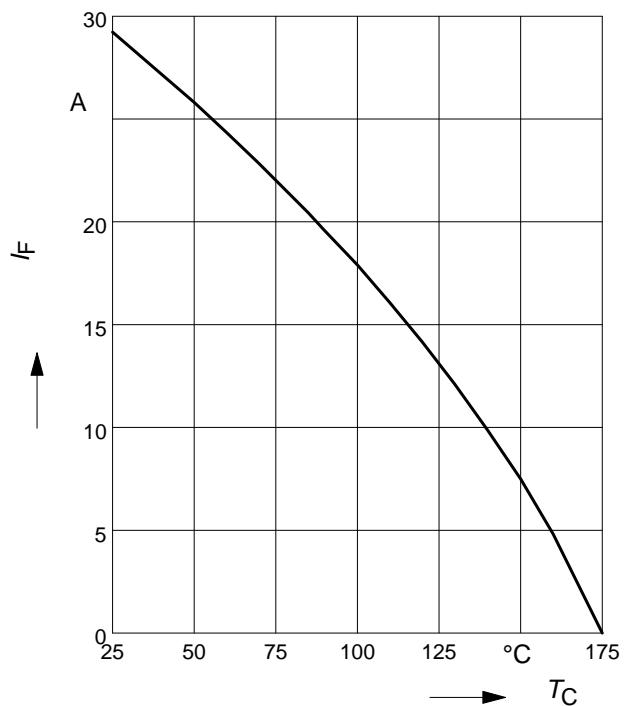
$$P_{\text{tot}} = f(T_C)$$

parameter:  $T_j \leq 175^\circ\text{C}$

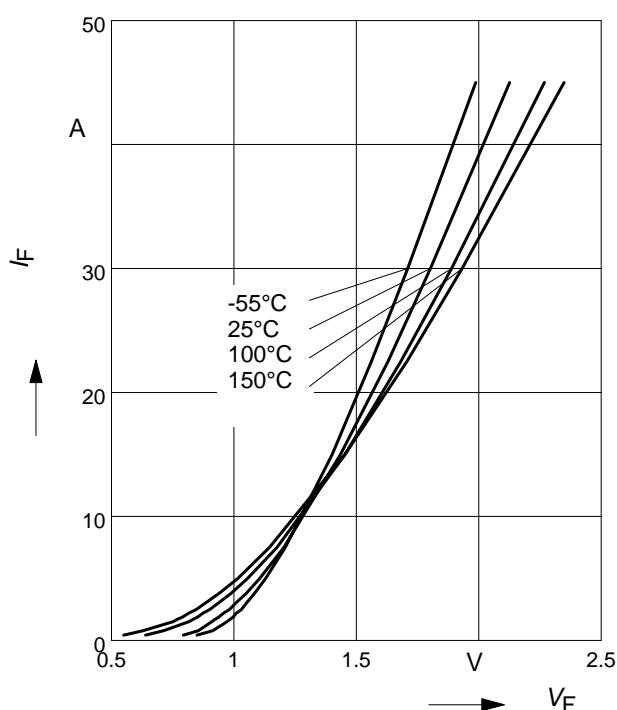

**2 Diode forward current**

$$I_F = f(T_C)$$

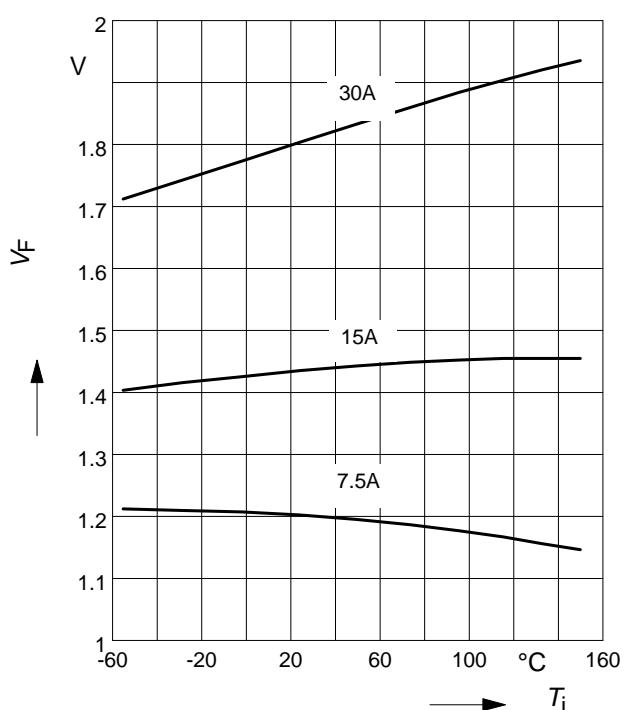
parameter:  $T_j \leq 175^\circ\text{C}$


**3 Typ. diode forward current**

$$I_F = f(V_F)$$


**4 Typ. diode forward voltage**

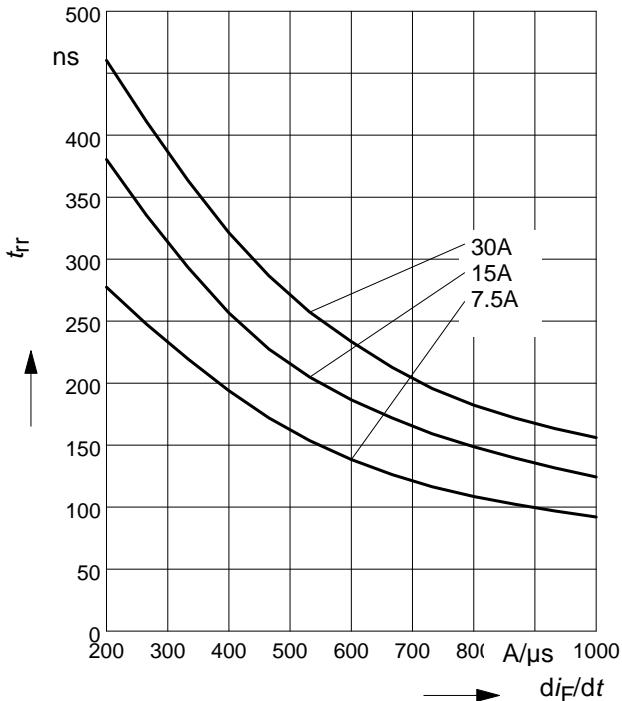
$$V_F = f(T_j)$$



### 5 Typ. reverse recovery time

$$t_{rr} = f(dI_F/dt)$$

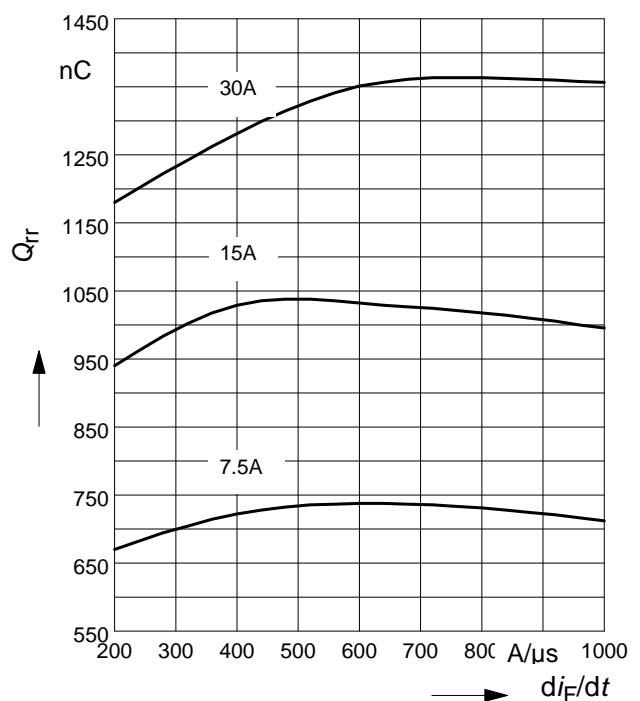
parameter:  $V_R = 400V$ ,  $T_j = 125^\circ C$



### 6 Typ. reverse recovery charge

$$Q_{rr} = f(dI_F/dt)$$

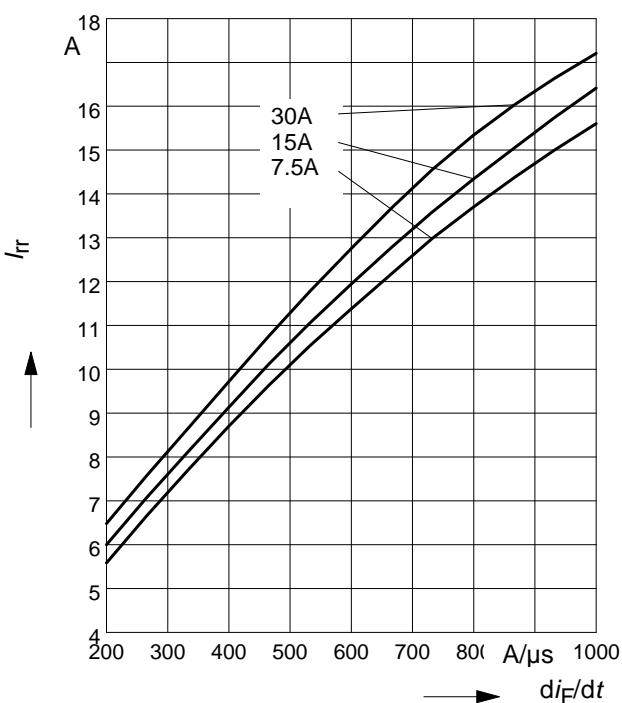
parameter:  $V_R = 400V$ ,  $T_j = 125^\circ C$



### 7 Typ. reverse recovery current

$$I_{rr} = f(dI_F/dt)$$

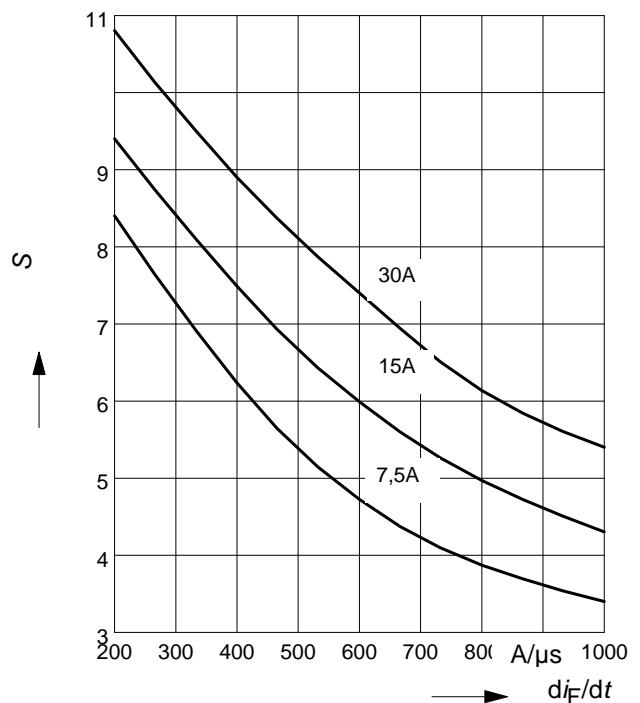
parameter:  $V_R = 400V$ ,  $T_j = 125^\circ C$



### 8 Typ. reverse recovery softness factor

$$S = f(dI_F/dt)$$

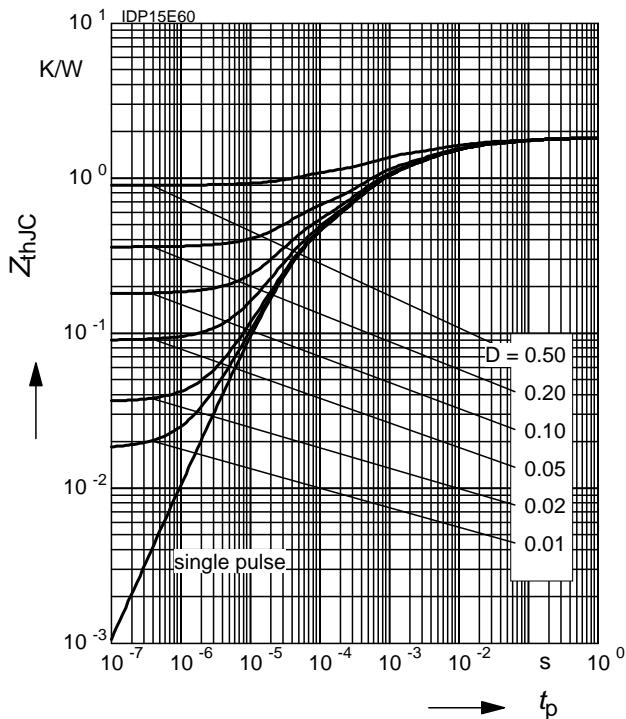
parameter:  $V_R = 400V$ ,  $T_j = 125^\circ C$

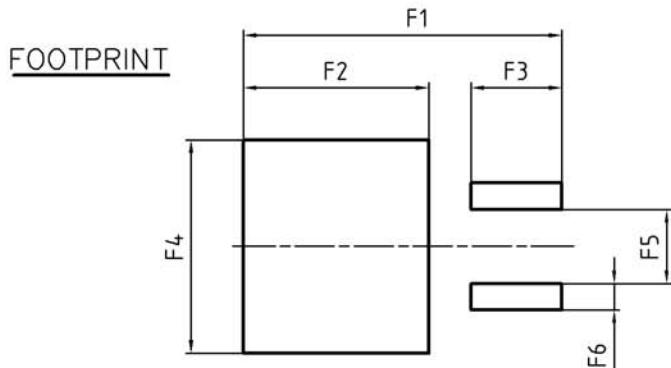
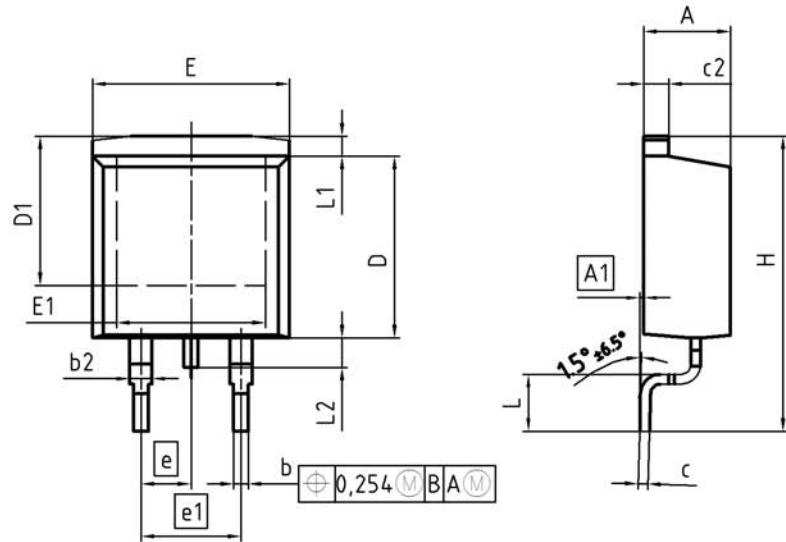


## 9 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

parameter :  $D = t_p/T$





| DIM | MILLIMETERS |       | INCHES |       |
|-----|-------------|-------|--------|-------|
|     | MIN         | MAX   | MIN    | MAX   |
| A   | 4.30        | 4.57  | 0.169  | 0.180 |
| A1  | 0.00        | 0.25  | 0.000  | 0.010 |
| b   | 0.65        | 0.85  | 0.026  | 0.033 |
| b2  | 0.95        | 1.15  | 0.037  | 0.045 |
| c   | 0.33        | 0.65  | 0.013  | 0.026 |
| c2  | 1.17        | 1.40  | 0.046  | 0.055 |
| D   | 8.51        | 9.45  | 0.335  | 0.372 |
| D1  | 7.10        | 7.90  | 0.280  | 0.311 |
| E   | 9.80        | 10.31 | 0.386  | 0.406 |
| E1  | 6.50        | 8.60  | 0.256  | 0.339 |
| e   | 2.54        |       | 0.100  |       |
| e1  | 5.08        |       | 0.200  |       |
| N   | 2           |       | 2      |       |
| H   | 14.61       | 15.88 | 0.575  | 0.625 |
| L   | 2.29        | 3.00  | 0.090  | 0.118 |
| L1  | 0.70        | 1.60  | 0.028  | 0.063 |
| L2  | 1.00        | 1.78  | 0.039  | 0.070 |
| F1  | 16.05       | 16.25 | 0.632  | 0.640 |
| F2  | 9.30        | 9.50  | 0.366  | 0.374 |
| F3  | 4.50        | 4.70  | 0.177  | 0.185 |
| F4  | 10.70       | 10.90 | 0.421  | 0.429 |
| F5  | 3.65        | 3.85  | 0.144  | 0.152 |
| F6  | 1.25        | 1.45  | 0.049  | 0.057 |

|                          |                     |
|--------------------------|---------------------|
| DOCUMENT NO.             | Z8B00003324         |
| SCALE                    | 0<br>0 5 5<br>7.5mm |
| EUROPEAN PROJECTION      |                     |
|                          |                     |
| ISSUE DATE<br>30-08-2007 |                     |
| REVISION<br>01           |                     |

**Published by**

**Infineon Technologies AG**  
**81726 Munich, Germany**  
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